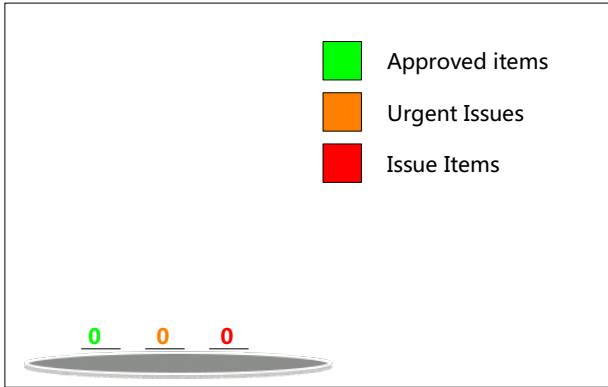


# HQDFM Design for Manufacture(DFM) Report

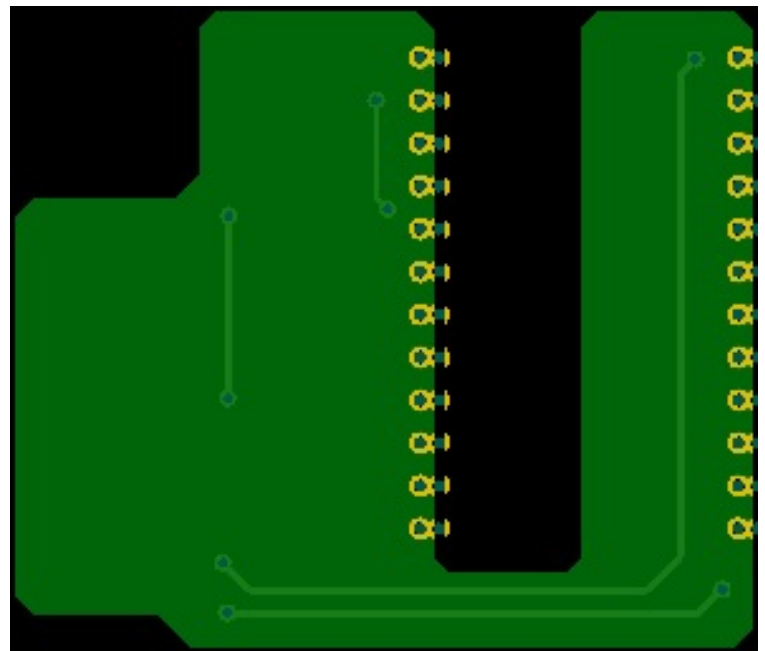
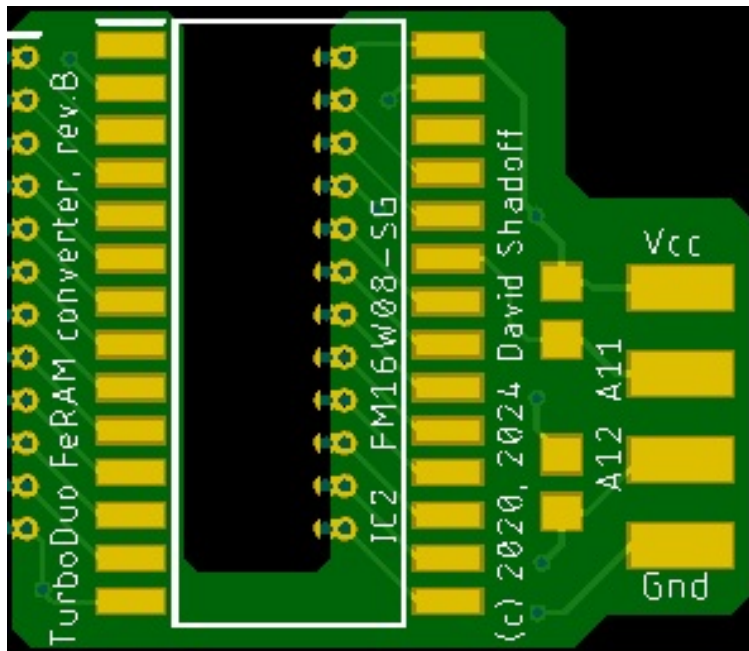
File name: 0000A789814\_1

Time: 2026-03-20 Layer count:2 PCB Thickness: 1.60 Quantity: 5 mm



Basic Board Specs	Trace Width/Spacing	6.00/8.00mil+
	Milling Density	
	Surface Finish Area	17.42%
	Test Point Count	
	Panel Efficiency	

The file size is small, which can affect the surface mount assembly process. It is recommended to have a size larger than 7\*7cm. You can optimize the size by adding a process edge or increasing the panelization.



Type	Category	No. of Checks	Result
General Analysis	Ipc Check	1	
	Types Devices	1	
PCB_SOLDERMASK	Solder Mask Analysis	3	Pass
	Missing Mask Opening	2	Pass
PCB_SILKSCREEN	Silkscreen Analysis	2	Pass
PCB_SIGNAL	Signal Integrity	5	Pass 2
	Smallest Trace Width	1	Pass 3
	Smallest Trace Spacing	4	Pass
	SMD Pad Spacing	2	Pass
	Pad Size	3	Pass
	Annular Ring Size	4	Fail 24
	Drill to Copper	4	Pass
	Copper/Edge Gap	3	Fail 24
	Drill On Pad	4	Pass
	Special Pad	1	Pass 1
	Hatched Copper	1	Pass
	Drill Size	14	Pass 6, Fail 1
PCB_DRILL	Drill Spacing	32	Pass
	Drill to Edge	4	Fail 48
	Special Drills	3	Fail 1

ID	Check	Limits	Value	Issue	Image	Position	Qty	Level
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